Printed Circuit Boards
Interconnection Carriers

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
06	227	FR4	35	L36.70	P18_06	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_227_FR4_35_L36.70_p18_06

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	B
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	B
	180µ	Prepreg		B
Layer-2	70µ	Copper		A1, B
	360µ	L-FR4		A1, B
Layer-3	70µ	Copper		A1, B
	180µ	Prepreg		B
	180µ	Prepreg		B
Layer-4	70µ	Copper		A2, B
	360µ	L-FR4		A2, B
Layer-5	70µ	Copper		A2, B
	180µ	Prepreg		B
	180µ	Prepreg		B
	60µ	Prepreg		B
Layer-99	35µ	Copper		B

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